PHB29N08T



N-channel TrenchMOS standard level FET

Rev. 03 — 13 October 2009

Product data sheet

1. Product profile

1.1 General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

1.2 Features and benefits

- High noise immunity due to high gate threshold voltage
- Low conduction losses due to low on-state resistance

1.3 Applications

Industrial motor control

1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C	-	-	75	V
I_D	drain current	T_{mb} = 25 °C; V_{GS} = 11 V; see <u>Figure 1</u> and <u>3</u>	-	-	27	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	-	88	W
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 10 \text{ V}; I_D = 29 \text{ A};$ $V_{DS} = 60 \text{ V}; T_j = 25 \text{ °C};$ see Figure 11	-	9	-	nC
Static ch	aracteristics					
R_{DSon}	drain-source on-state resistance	$V_{GS} = 11 \text{ V; } I_D = 14 \text{ A;}$ $T_j = 175 \text{ °C; see } \frac{\text{Figure 9}}{\text{Model}} \text{ and } \frac{10}{\text{Model}}$	-	96	120	mΩ
		$V_{GS} = 11 \text{ V; } I_D = 14 \text{ A; } T_j = 25 \text{ °C;}$ see Figure 9 and $\underline{10}$	-	40	50	mΩ



2. Pinning information

Table 2. Pinning information

	_				
Pin	Symbol	Description		Simplified outline	Graphic symbol
1	G	gate			
2	D	drain	<u>[1]</u>	mb	D
3	S	source			$G \longrightarrow A$
mb D	D	mounting base, connected to drain		1 3	mbb076 S
				SOT404 (D2PAK)	

[1] It is not possible to make connection to pin 2.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PHB29N08T	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

4. Limiting values

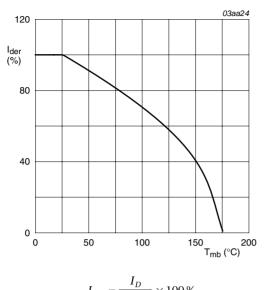
Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C	-	75	V
V_{DGR}	drain-gate voltage	$T_j \le 175 \text{ °C}; T_j \ge 25 \text{ °C}; R_{GS} = 20 \text{ k}\Omega$	-	75	V
V_{GS}	gate-source voltage		-30	30	V
I _D	drain current	$V_{GS} = 11 \text{ V; } T_{mb} = 100 \text{ °C; see } \frac{\text{Figure 1}}{}$	-	19.2	Α
		V_{GS} = 11 V; T_{mb} = 25 °C; see <u>Figure 1</u> and <u>3</u>	-	27	Α
I _{DM}	peak drain current	$t_p \le 10 \mu\text{s}; \text{ pulsed}; T_{mb} = 25 ^{\circ}\text{C}; \text{ see } \frac{\text{Figure 3}}{}$	-	108	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	88	W
T _{stg}	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
Source-dr	ain diode				
Is	source current	T _{mb} = 25 °C	-	27	Α
I _{SM}	peak source current	$t_p \le 10 \mu\text{s}; \text{ pulsed}; T_{mb} = 25 ^{\circ}\text{C}$	-	108	Α

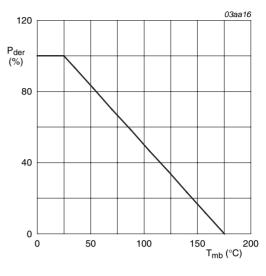
Nexperia PHB29N08T

N-channel TrenchMOS standard level FET



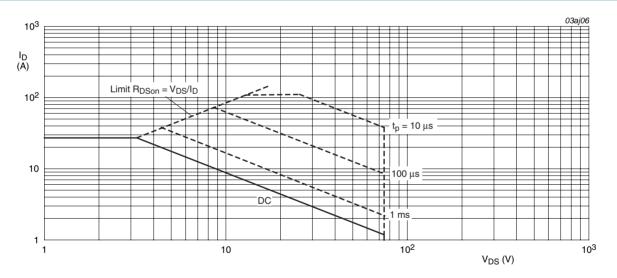
 $I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$

Fig 1. Normalized continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



 $T_{mb} = 25$ °C; I_{DM} is single pulse; $V_{GS} = 11V$

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see <u>Figure 4</u>	-	-	1.7	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	SOT404 minimum footprint; mounted on a printed-circuit board	-	50	-	K/W

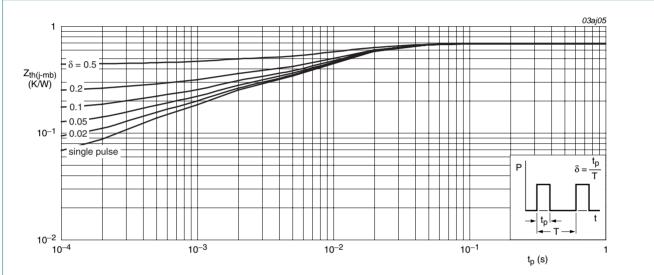


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics					
V _{(BR)DSS}	drain-source	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ °C}$	70	-	-	V
breakdown voltage		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	75	-	-	V
$V_{GS(th)}$ gate-source threshold voltage	$I_D = 2$ mA; $V_{DS} = V_{GS}$; $T_j = 175$ °C; see Figure 8	2.1	-	-	V	
		$I_D = 2 \text{ mA}$; $V_{DS} = V_{GS}$; $T_j = -55 \text{ °C}$; see Figure 8	-	-	5.4	V
		$I_D = 2$ mA; $V_{DS} = V_{GS}$; $T_j = 25$ °C; see <u>Figure 8</u>	3	4	5	V
I _{DSS}	drain leakage current	$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	0.05	10	μΑ
		V _{DS} = 75 V; V _{GS} = 0 V; T _j = 175 °C	-	-	500	μΑ
I _{GSS}	gate leakage current	$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	10	100	nΑ
		$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	10	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 11 V; I_{D} = 14 A; T_{j} = 175 °C; see Figure 9 and 10	-	96	120	mΩ
		V_{GS} = 11 V; I_{D} = 14 A; T_{j} = 25 °C; see <u>Figure 9</u> and <u>10</u>	-	40	50	mΩ
Dynamic	characteristics					
Q _{G(tot)}	total gate charge	$I_D = 29 \text{ A}; V_{DS} = 60 \text{ V}; V_{GS} = 10 \text{ V};$	-	19	-	nC
Q_{GS}	gate-source charge	$T_j = 25 ^{\circ}\text{C}$; see Figure 11	-	6	-	nC
Q_{GD}	gate-drain charge		-	9	-	nC
C _{iss}	input capacitance	$V_{DS} = 25 \text{ V}; V_{GS} = 0 \text{ V}; f = 1 \text{ MHz};$	-	810	-	pF
C _{oss}	output capacitance	T _j = 25 °C; see <u>Figure 12</u>	-	140	-	pF
C _{rss}	reverse transfer capacitance		-	85	-	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 38 \text{ V}; R_L = 1.3 \Omega; V_{GS} = 10 \text{ V};$	-	9.5	-	ns
t _r	rise time	$R_{G(ext)} = 5.6 \Omega; T_j = 25 \text{ °C}; I_D = 29 A$	-	70	-	ns
t _{d(off)}	turn-off delay time		-	15	-	ns
t _f	fall time		-	9	-	ns
Source-d	rain diode					
V_{SD}	source-drain voltage	$I_S = 14 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C};$ see <u>Figure 13</u>	-	0.95	1.2	V
t _{rr}	reverse recovery time	I_S = 14 A; dI_S/dt = -100 A/ μ s; V_{GS} = 0 V; V_{DS} = 25 V; T_i = 25 °C	-	50	-	ns

Nexperia PHB29N08T

N-channel TrenchMOS standard level FET

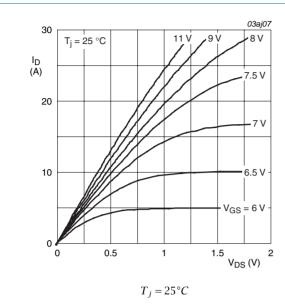


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

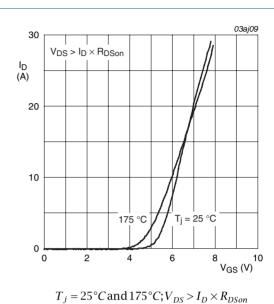


Fig 6. Transfer characteristics: drain current as a

function of gate-source voltage; typical values

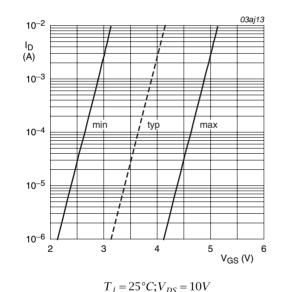


Fig 7. Sub-threshold drain current as a function of gate-source voltage

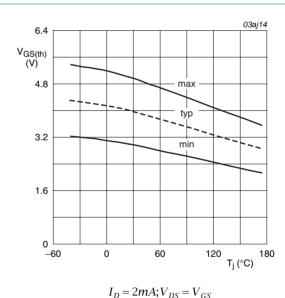


Fig 8. Gate-source threshold voltage as a function of junction temperature

Nexperia PHB29N08T

N-channel TrenchMOS standard level FET

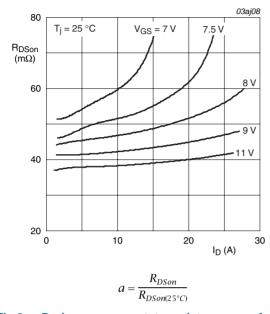


Fig 9. Drain-source on-state resistance as a function of drain current; typical value

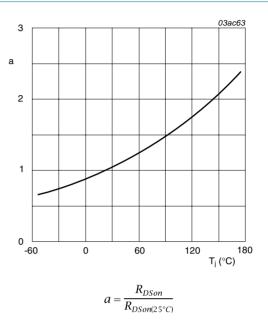


Fig 10. Normalized drain-source on-state resistance factor as a function of junction temperature

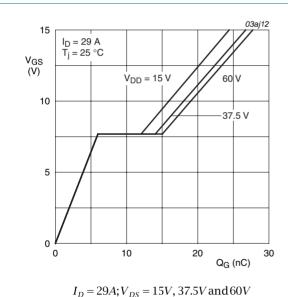


Fig 11. Gate-source voltage as a function of gate charge; typical values

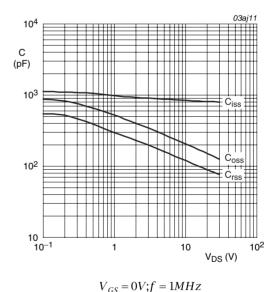
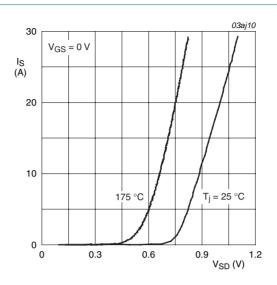


Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

7 of 12



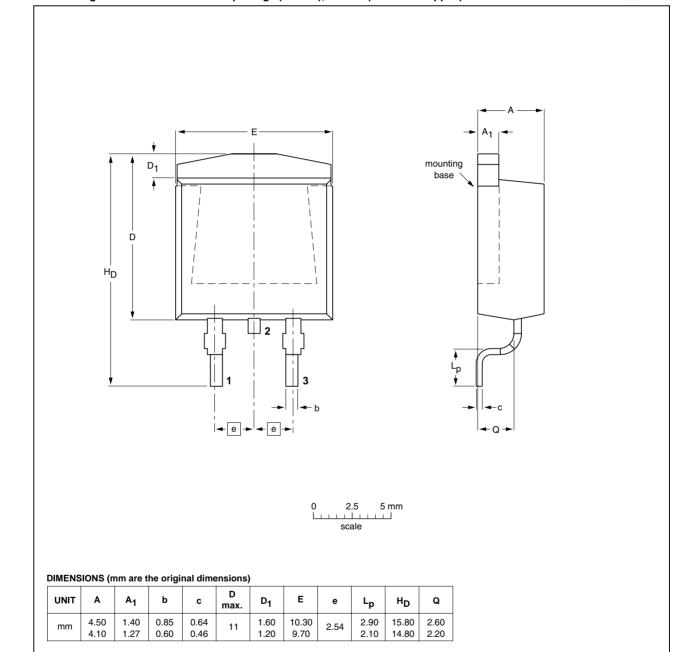
 $T_j = 25$ °C and 175°C; $V_{GS} = 0V$

Fig 13. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

SOT404



OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT404					-05-02-11

Fig 14. Package outline SOT404 (D2PAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PHB29N08T_3	20091013	Product data sheet	-	PHB29N08T_2
Modifications:	 Various cha 	anges to content.		
PHB29N08T_2	20090310	Product data sheet	-	PHP_PHB29N08T-01
PHP_PHB29N08T-01 (9397 750 09651)	20020529	Product data	-	-

9. Legal information

9.1 Data sheet status

Document status [1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

9.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

9.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — Nexperia products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of a Nexperia product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Nexperia accepts no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — Nexperia products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nexperia.com/profile/terms, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by Nexperia. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

9.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

10. Contact information

For more information, please visit: http://www.nexperia.com

For sales office addresses, please send an email to: salesaddresses@nexperia.com

Nexperia

PHB29N08T

N-channel TrenchMOS standard level FET

11. Contents

1	Product profile
1.1	General description
1.2	Features and benefits
1.3	Applications1
1.4	Quick reference data1
2	Pinning information2
3	Ordering information2
4	Limiting values2
5	Thermal characteristics4
6	Characteristics5
7	Package outline
8	Revision history10
9	Legal information11
9.1	Data sheet status
9.2	Definitions11
9.3	Disclaimers
9.4	Trademarks11
10	Contact information

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Nexperia manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 2N7000 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D

TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C

IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI

DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384

NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956

NTE2911 US6M2GTR TK10A80W,S4X(S SSM6P69NU,LF